

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT6225868

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHUTESH KRISHNAN	07/20/2017
SW WANG	07/20/2017
CH CHEW	07/20/2017
HOW KIAT LIEW	07/20/2017
FUI FUI TAN	07/20/2017
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Street Address:	5005 EAST MCDOWELL ROAD, MD A700
City:	PHOENIX
State/Country:	ARIZONA
Postal Code:	85008
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16942916
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ATTORNEY DOCKET NUMBER:	ONS02432DC01US
NAME OF SUBMITTER:	KELLY A. HALL
SIGNATURE:	/Kelly A. Hall/
DATE SIGNED:	07/30/2020
Total Attachments: 3	

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ASSIGNMENT & AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	of (City and State OR Country)
Shutesh KRISHNAN	Negeri Sembilan Malaysia
Sw WANG	Seremban Malaysia
CH CHEW	Seremban Malaysia
How Kiat LIEW	Bukit Jalil Malaysia
Fui Fui TAN	Seremban Malaysia

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

Title: THIN SEMICONDUCTOR PACKAGE AND RELATED METHODS

Attorney Docket No.: ONS02432US

Serial No.: 15/679664

Filing Date: August 17, 2017

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

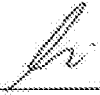
We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

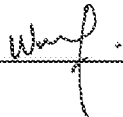
We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

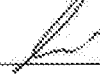
By (Inventor signature): 
Shutesh KRISHNAN

Witnessed by (Witness signature): 

Printed name of Witness: Liong Jin Yoong

Signed and Witnessed on (date): 20 JUL 2017

By (Inventor signature): 
Sw WANG

Witnessed by (Witness signature): 

Printed name of Witness: Liong Jin Yoong


Signed and Witnessed on (date): 20 JUL 2017


By (Inventor signature): 
CH CHEW

Witnessed by (Witness signature): 

Printed name of Witness: Liong Jin Yoong

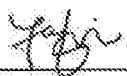
Signed and Witnessed on (date): 20 JUL 2017

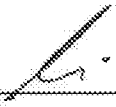
By (Inventor signature): 
How Kiat LIEW

Witnessed by (Witness signature): 

Printed name of Witness: Liong Jin Yoong

Signed and Witnessed on (date): 20 JUL 2017

By (Inventor signature): 
Fui Fui TAN

Witnessed by (Witness signature): 

Printed name of Witness: Liang Jin Yoong

Signed and Witnessed on (date): 20 JUL 2017
